

Serial No.09/614,993

Docket No.: 55085US002

Amendments to the Claims

A detailed list of all claims under examination is set out below. Please amend claims 38-40 and 43 as shown below in marked form, and add new claims 44-60 as shown below:

1-37. (Cancelled)

38. (currently amended): The article of claim 43 wherein the adhesive is selected from the group comprising comprises a hot melt adhesive, pressure sensitive adhesives adhesive, curable adhesives adhesive, and or filled adhesives adhesive.

39. (currently amended): The article of claim 38 wherein the filled adhesive is selected from the group comprising comprises a filled electrically conductive adhesives adhesive, thermally conductive adhesives adhesive, and or desiccating adhesives adhesive.

40. (currently amended): The article of claim 43 wherein the circumference of the adhesive layer is greater than that of an electrode there is a gap between the multi-layer structure and the surrounding adhesive.

41. (previously presented): The article of claim 43 wherein the article is an organic light emitting diode.

42. (previously presented): The article of claim 44 wherein the substrate comprises glass, the anode comprises indium tin oxide, the hole transporting layer comprises 4,4'-bis(naphthalen-2-yl)-N,N'-diphenyl benzidine, the light emitting layer comprises coumarin-doped tris(8-hydroxyquinolinato)aluminum, the electron transporting layer comprises bis(10-hydroxy-benzo(h)quinolinato) beryllium, bis(2-(2-hydroxy-phenyl)-benzolthiazolato) zinc, 3,4,5-triphenyl-1,2,4-triazole, or 2-(4-biphenylyl)-5-(4-t-butylphenyl)-1,3,4-oxadiazole, and the cathode comprises lithium fluoride and aluminum.

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43. (currently amended): An article comprising an organic electronic device which comprises:

- a. a substrate;
- b. a patterned an adhesive on the substrate;
- c. a multi-layer structure comprising one or more organic layers

between an anode and a cathode, the anode, cathode or an organic layer having at least one outer edge wherein the adhesive surrounds the multi-layer structure; and

- d. a sealing layer; and

wherein the adhesive is equal to the circumference of one or both of the substrate or sealing layer seals an outer edge of an organic layer and has an opening through the adhesive that surrounds the multi-layer structure.

44. (previously presented): The article of claim 43 wherein the organic layers comprise a hole transporting layer, a light emitting layer, and an electron transporting layer.

45. (new): The article of claim 40 further comprising a desiccant in the gap.

46. (new): The article of claim 43 wherein the adhesive seals an outer edge of an anode or cathode.

47. (new): The article of claim 43 wherein the adhesive seals all outer edges of an organic layer.

48. (new): The article of claim 43 wherein the adhesive seals all outer edges of the multi-layer structure.

49. (new): The article of claim 43 wherein the adhesive improves the device's structural stability.

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50. (new): The article of claim 43 wherein the adhesive and multi-layer structure have approximately equal thicknesses.

51. (new): The article of claim 43 wherein the adhesive thickness is greater than the multi-layer structure thickness.

52. (new): The article of claim 43 wherein the adhesive is on the substrate and the sealing layer is on the adhesive.

53. (new): The article of claim 43 wherein the multi-layer structure is encapsulated by the adhesive and sandwiched between the substrate and sealing layer.

54. (new): An article comprising an organic electronic device which comprises:

- a. a roll of flexible substrate;
- b. an adhesive;
- c. a release liner; and
- d. a multi-layer structure comprising one or more organic layers

between an anode and a cathode, the anode, cathode or an organic layer having at least one outer edge;

wherein the adhesive and release liner have a combined thickness greater than the multi-layer structure thickness, and protect the multi-layer structure from damage in a roll to roll manufacturing process; and wherein the adhesive has an opening through it that surrounds the multi-layer structure.

55. (new): The article of claim 54 wherein the adhesive seals an outer edge of an anode or cathode.

56. (new): The article of claim 54 wherein the adhesive seals an outer edge of an organic layer.

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57. (new): The article of claim 54 wherein the adhesive seals all outer edges of an organic layer.

58. (new): The article of claim 54 wherein the adhesive seals all outer edges of the multi-layer structure.

59. (new): The article of claim 54 wherein the adhesive and multi-layer structure have approximately equal thicknesses.

60. (new): The article of claim 54 wherein the adhesive and release liner have complementary openings.